SCIENTECH

Scientech Corp (3583:TT)

M.T. Hsu 2025/12/16

Safe Harbor Statement

SCIENTECH

- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.

- Except as required by law, we undertake no obligation to update any forward-looking statements, whether as a result of new information, future events or otherwise.

Agenda

SCIENTECH

- Company Profile
- Products
- Corporate Governance
- Financial Results
- Future Prospect

ABOUT US

Overview | Milestones | Location | Certificate | Competence

Overview

SCIENTECH

Product and Technology

- Equipment Design and Manufacturing
- Wafer Reclaim
- Representative

Industries We Serve

- Semiconductor (Front-End and Advanced Packaging)
- Compound Semiconductor
- LED / Mini LED / Micro LED
- Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)

Established:
1979
Taipei, Taiwan

Capital:
US$ 27 Million
TWSE:3583

Employees:
>1,150
(Worldwide)

Staffs

Over 1,150 Staffs

Representative

- 140 in Taiwan
- 130 in China
- 70% in Service and Process Support

Equipment Design and Maf’g

- 475 in Total
- 166+ in R&D, Process and Design

Wafer Reclaim

- 320 in Total

Administration

- 85 in Total

Milestones

SCIENTECH

1979

1985
Branch Office
in Hsinchu, Taiwan

1995
Subsidiary
in CA, USA

2001
Subsidiary
in Shanghai, China

2002
Singapore

2003
Equipment Manufacture
Department Established

2004
New Hsinchu
Office Opened

2006
Wafer Reclaim
Business Launched

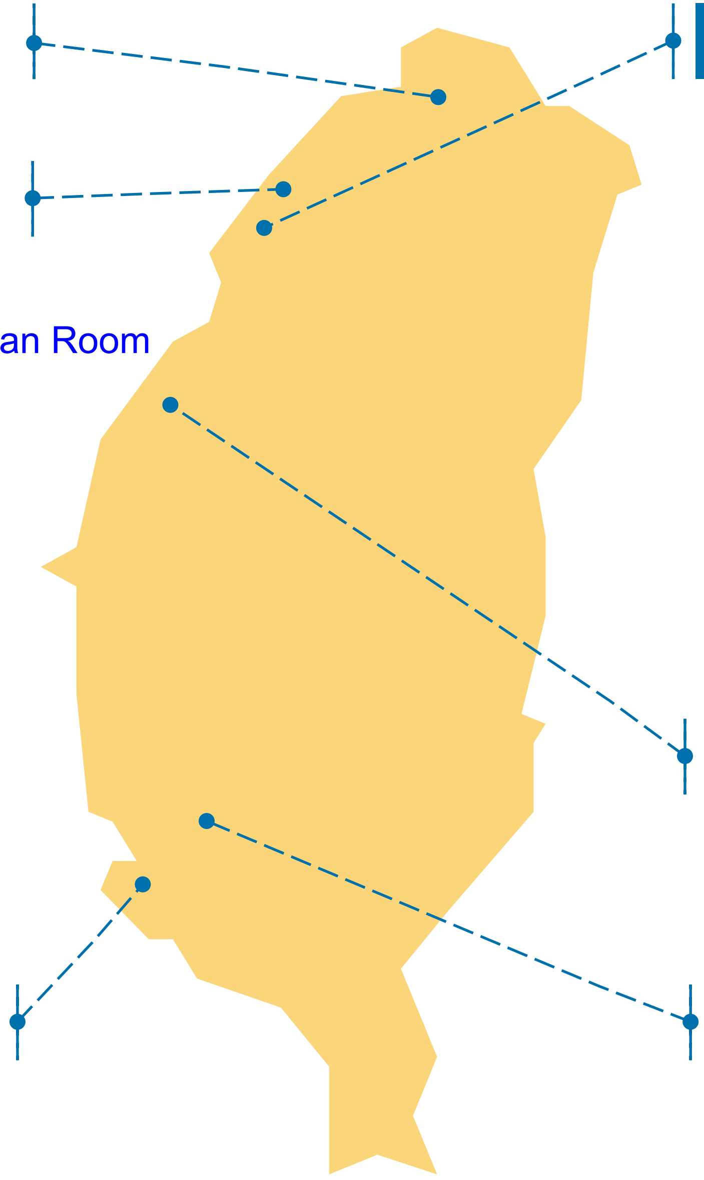
2007
New Factory
in Hukou Opened

2013
Publicly Listed in
Taiwan Stock Market

2019
Over 500 Equipment
Sales Achievement

2021
Subsidiary
in Villach, Austria

Locations - Taiwan



Taipei Headquarter

HuKou Factory

- Equipment Design and Manufacturing
  - Equipped With Class 10/1,000/10,000 Clean Room
- Wafer Reclaim

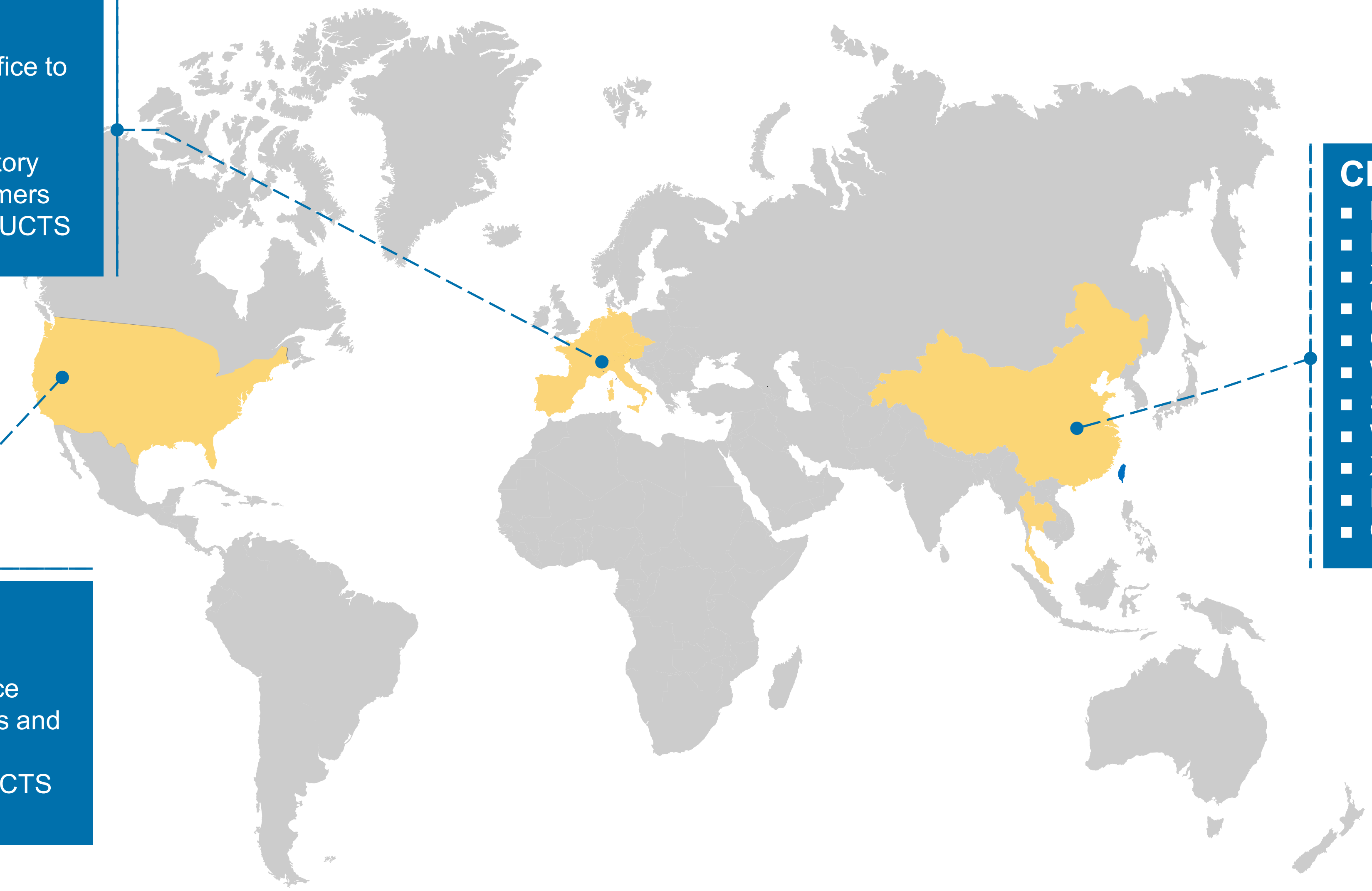
Kaohsiung Office

HsinChu Office

Taichung Office

Tainan Office

Locations - Worldwide



Europe

Villach, Austria (2020)

- Sales and Service Office to support European customers
- Interface with our factory and European Customers
- New Product / PRODUCTS Development

China

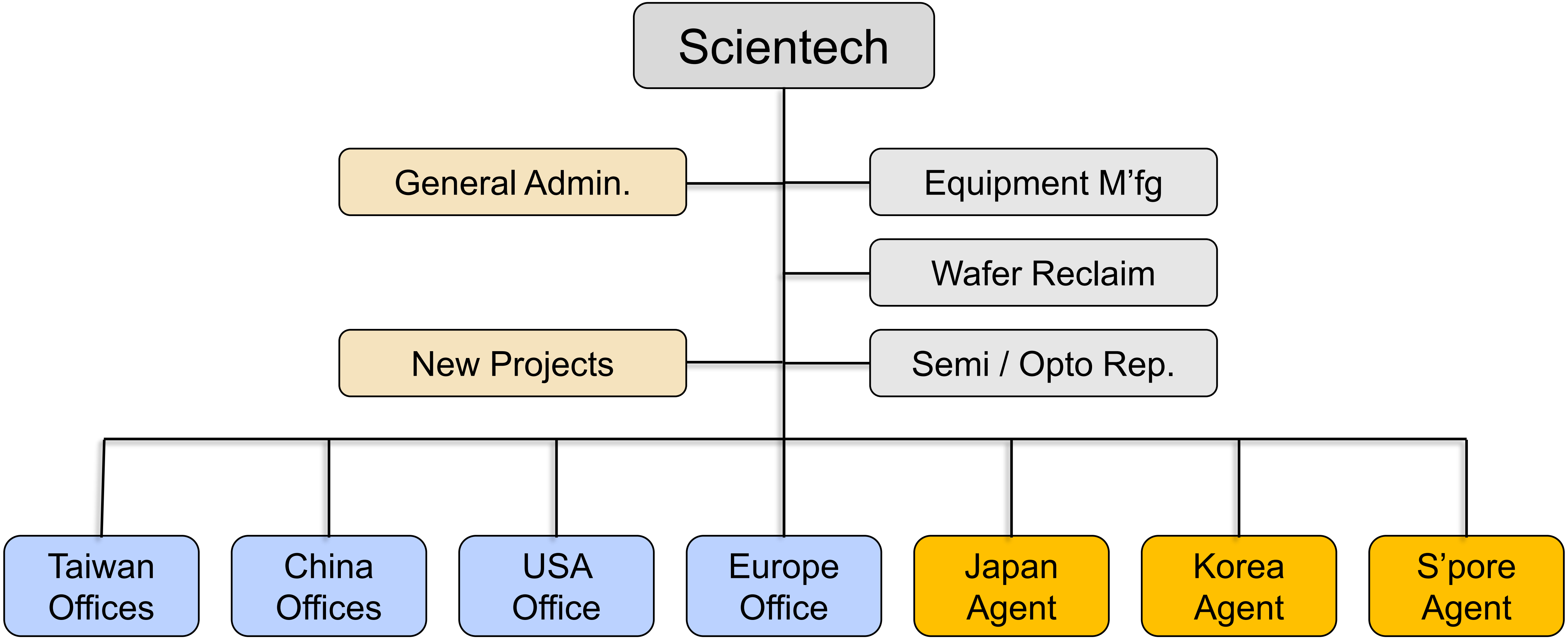
- Beijing office (2004)
- Dalian office (2012)
- Xian (2013)
- Chongqing office (2010)
- Changzhou (2012)
- Wuxi office (2003)
- Shanghai Office (2001)
- Wuhu office (2013)
- Xiamen office (2011)
- Huizhou office (2013)
- Qunming Office (2002)

USA

Santa Clara, CA (1994)

- Sales and Service Office
- Interface with Principals and U.S. Customers
- New Product / PRODUCTS Development

Organization

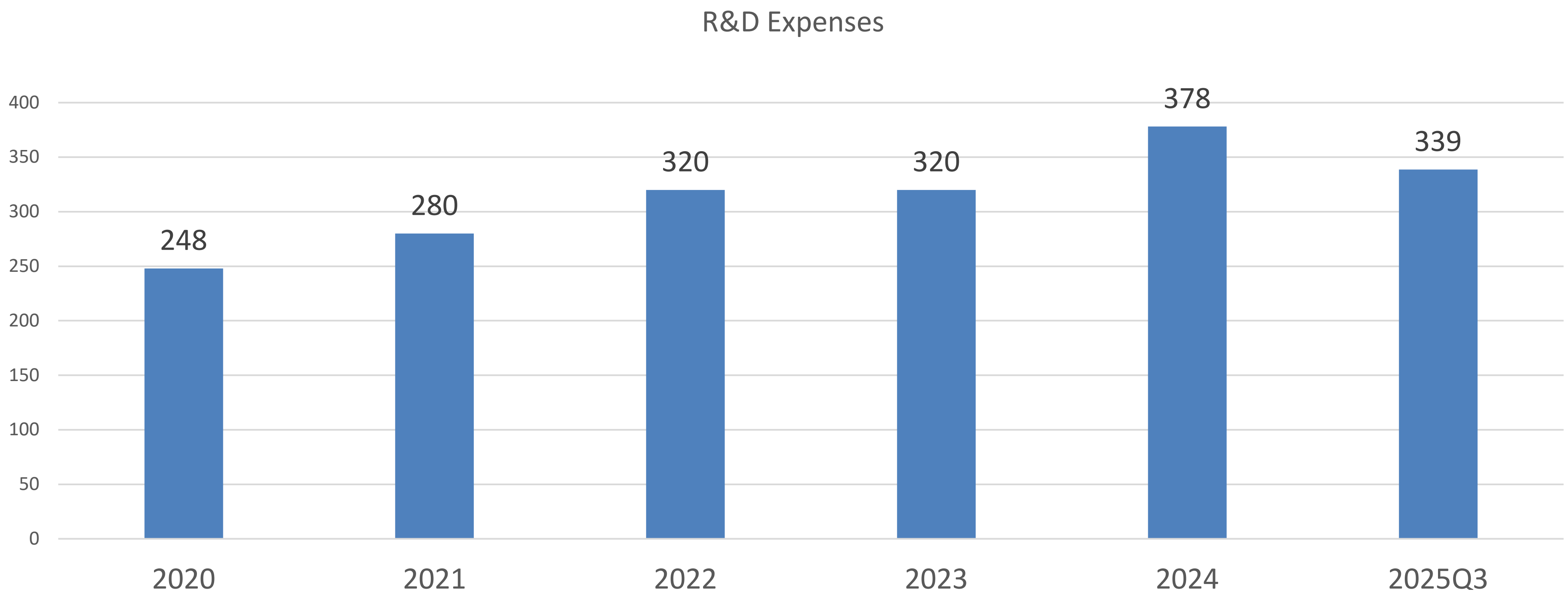


PRODUCTS

Wafer Reclaim | Equipment Manufacturing and Design | Representative

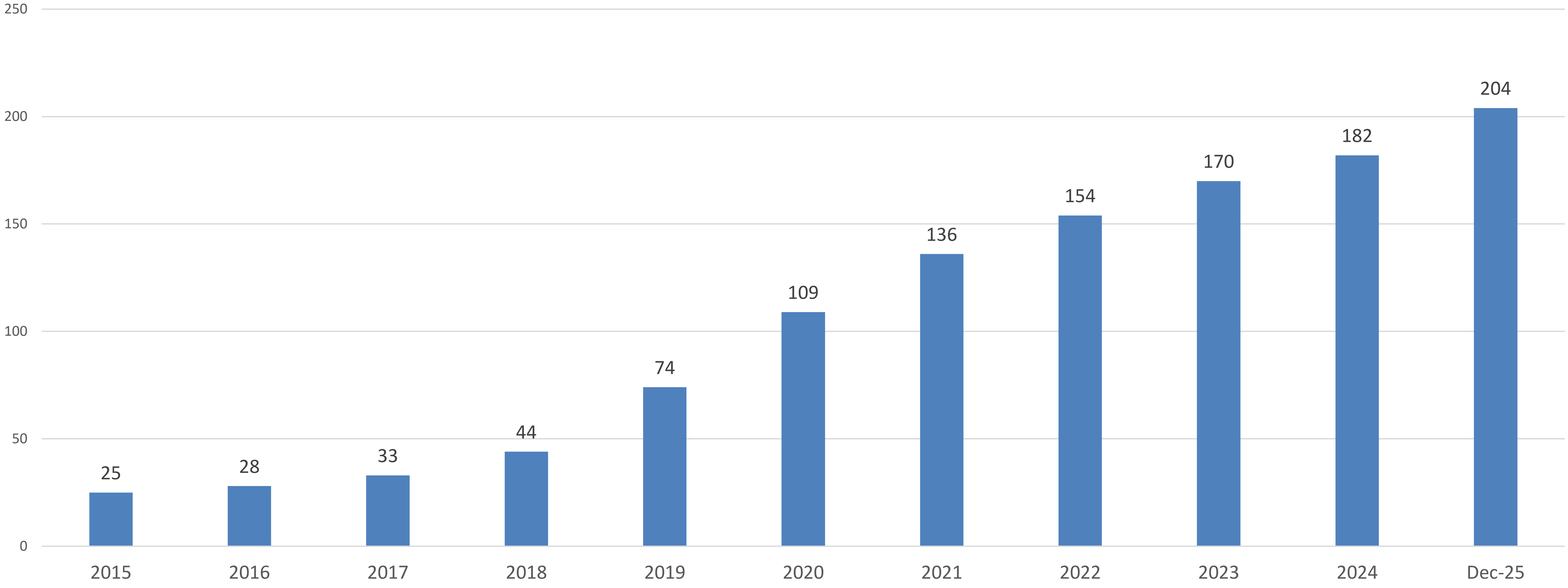
R&D Expenses

Units NT $ M	2020	2021	2022	2023	2024	2025Q3
R&D Expenses	248	280	320	341	378	339
Expenses as % of Revenue	6.9%	6.0%	5.7%	4.9%	3.9%	4.0%
Expenses as % of Manufacturing	16.5%	14.9%	15.3%	15.7%	11.3%	9.9%



研發專利累積數

- **The cumulative number of patents on file is 204, and 50 applications are pending.**



Products

Equipment Design and Manufacturing

- Advanced Package
- FEOL
- Mask
- Compound
- etc...

Wafer Reclaim

- 12” Si Wafer

Representative

- Equipment/Metrology
- Sub-System
- Material
- Repair and Refurbish

Wafer Reclaim Service

Advanced Clean Technology
- **19nm Particle**
- **Low Trace Metal (<1E9)**

Advanced Defect Inspection (SP1/SP2/SP5/SP7)

12” Si Wafer

- Capacity: 210K / Month
- Cu and Non-Cu Process

Capacity Expansion

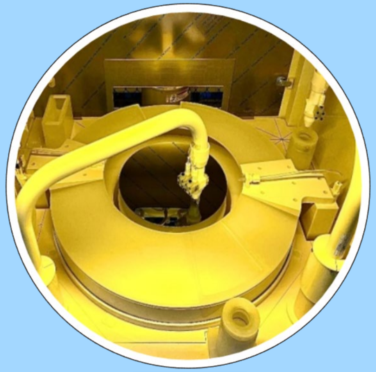
- Additional 40K / Month by end of 2026

Complete Polishing Process
- **Single/Double Side Polish**
- **Final Haze Polish**

Super Flatness (GBIR < 0.5mm)

Equipment Design & Manufacturing

Wet Bench



Single Wafer

TBDB

Baking

Wet Process – Bench

Application

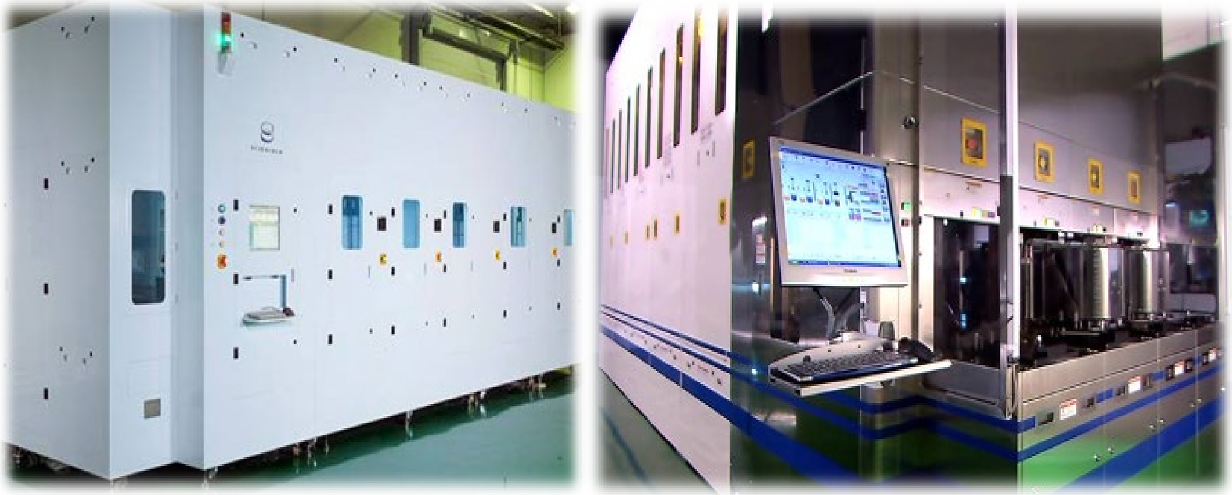
- Semiconductor: FEOL, BEOL, Compound
- Advanced Packaging/Bumping…

Features

- Cassette type or Cassette-less type
- Adopted by big international companies
- Leading-edge technologies

Process

- Etch: Metal/Oxide/Nitride remove
- Stripper: PR/PI strip, Polymer remove
- Clean: Pre/Post/Flux clean
- Electro-less Plating: Zn/Ni/Pd/Au



Wet Process – Single Wafer

Application

- Semiconductor: BEOL, FEOL, Compound
- Advanced Packaging/Bumping

Features

- Soak/Immersion + Single
- Adopted by big international companies
- Leading-edge technologies

Process

- UBM / Metal Etch
- Flux Clean (Hot DIW)
- PR Strip
- Wafer Clean (APC, Soft spray)
- Final Clean/Mask Clean/Frame Clean

Temporary Bonding De-Bonding

Application

- IGBT & SiC Power Device
- Advanced Packaging for Semiconductor

Features

- User-friendly graphical user interface
- Adopted by big international companies
- Leading-edge technologies

Process

- Temporary Bonding
- Temporary De-bonding
- Release Layer Coating
- Carrier (Glass) Recycling

Moisture Baking

Application

- Semiconductor: BEOL
- Advanced Packaging for Semiconductor

Features

- Availability for horizontal or vertical process
- High precision temperature control
- Weight handling capacity up to 23kg per lot

Process

- Pre-underfill baking
- Pre-mold baking
- DFR Hard Bake

Trading (Agent/Distributor)

TMC

BRUKER

Vistec
Electron Beam

MueTec
Measurement and Inspection

HPSP
High Pressure Solution Provider

Canon

Trymax
PLASMA TECHNOLOGY SOLUTIONS

NOVA
PROCESS INSIGHT

KLA

MDC
VACUUM PRODUCTS, LLC

SMEE

ZEISS

ADVANCED ENERGY

USHIO

Multiple Apps

Exclusivity

Long Term Partnership

Plasma-Therm

VLSI Standards Incorporated

RUDOLPH RESEARCH ANALYTICAL

TMC

YES

FRT

KINGSEMI

FILMETRICS

ExOne
DIGITAL PART MATERIALIZATION

Kensington
LABORATORIES

Verity
INSTRUMENTS, INC.

Representative Product Lines

Lithography

KINGSEMI

SMEE

vistec
Electron Beam

ESOL

USHIO

Etch

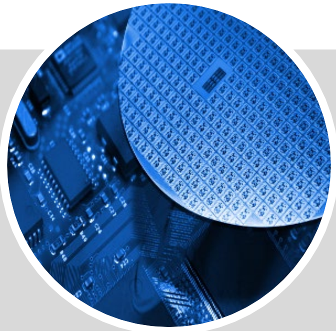
Plasma-Therm

CORIAL

Trymax
PLASMA TECHNOLOGY SOLUTIONS

NEMS tek
GLOW THE FUTURE

Verity
INSTRUMENTS, INC.



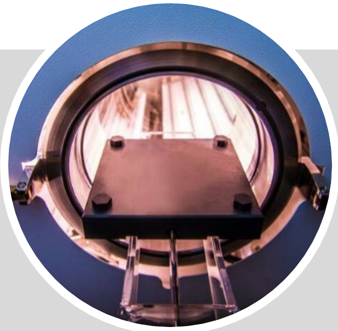
Thin Film

ClassOne
TECHNOLOGY

IntlVAC
THIN FILM

ProOptics

AXUS
TECHNOLOGY



Diffusion

HPSP
High Pressure Solution Provider

Representative Product Lines

Metrology

KLA
FILMETRICS
ZEISS
Camtek See Beyond
VLSI Standards Incorporated
MueTec Measurement and Inspection
SURUGA SEIKI
YAYATECH Technology . Innovation . Service
Rigaku
Toho Technology

Sub-Systems

Advanced Energy
MDC PRECISION
TMC VIBRATION CONTROL / AMETEK
Verity INSTRUMENTS, INC.
CORE INSIGHT 코어인사이트(주)
UNEO
AMETEK
Haydon kerk Motion Solutions
PITTMAN

Package & Material

PacTech member of nagase group
sempro
SANYOSEIKO CO.,LTD.
MIRTEC
MODU TECH
群翊 GROUP
M Napra
AMC Quality & Service
Cygnus
Univertical Global Benchmark of Quality

Robot Repair and Refurbish

Genmark
Kensington LABORATORIES
MILARA
Dynatronix

Corporate Governance

Certificates

Year	Certificate	Scope
2007	ISO 9001	Quality Management
2010	ISO 14001	Environmental Management
2016	ISO 45001	Occupational Health and Safety Management
2019	ISO 27001	Information Security Management
2021	ISO 22301	Business Continuity Management
2022	RBA	Responsible Business Alliance Online Member
2024	ISO 50001	Energy Management
2025	ISO56005	Innovation Management

ESG

Sustainability Report Officially Released in 2024/08

Sustainable Development

Environmental
Social
Governance

Eco-Friendly Manufacturing

Safe And Warm Working Environment

Operating With Integrity

Contributing To Society

Exhibition

SEMICON®

Semicon China

Mar. 26-28, 2025
Shanghai

SEMICON®

Semicon TW

Sep. 10-12, 2025
Taipei

SEMICON®

Semicon West

Oct. 07–09, 2025
Phoenix

SEMICON®

Semicon Europa

Nov. 18-21, 2025
Munich

Exhibition

INTERNATIONAL SEMICONDUCTOR EXECUTIVE SUMMITS TAIWAN

ISES

May 13-14, 2025
Taipei

ECTC

ECTC

May 27-30, 2025
Dallas, Texas

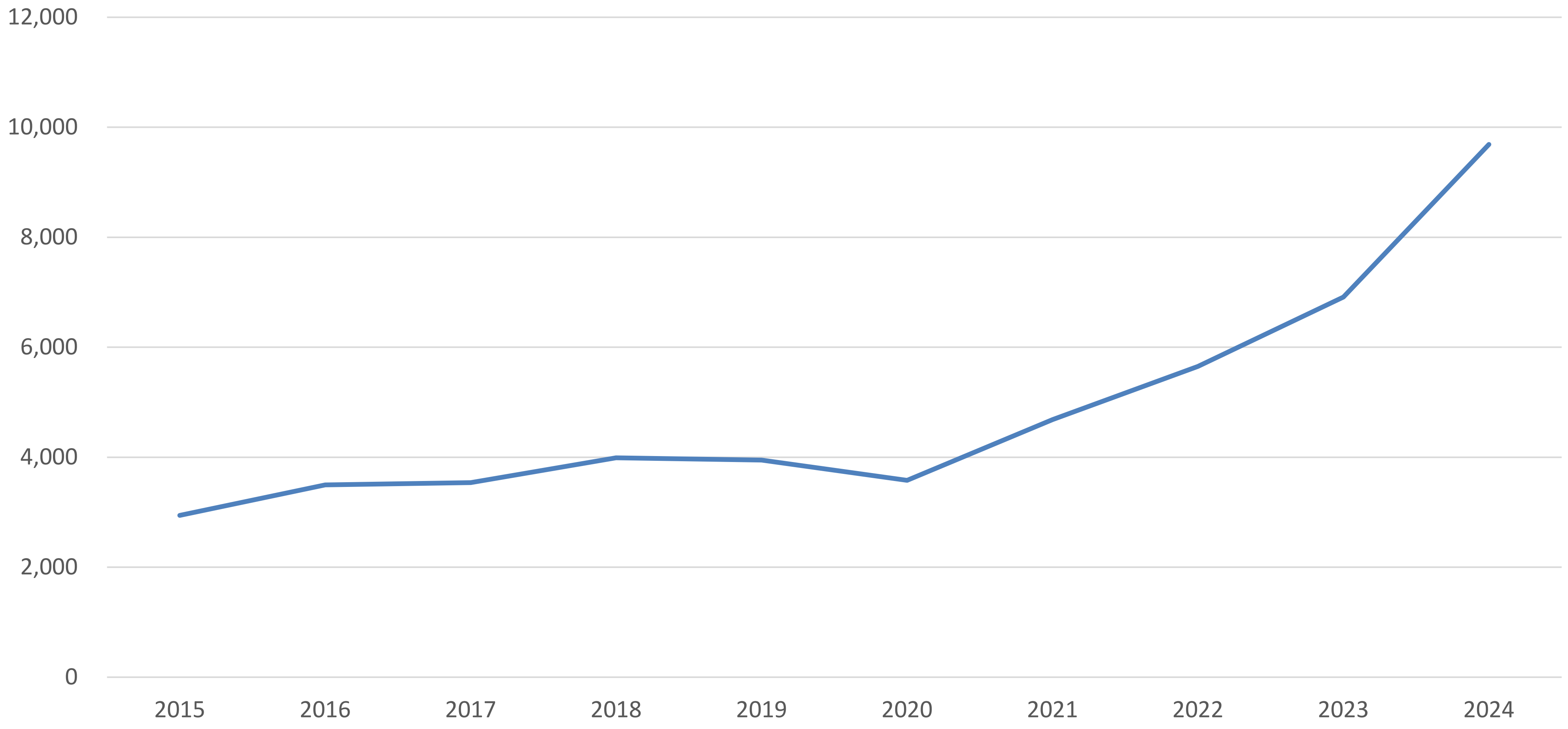
Financial Results

Income Statement

Units：NT $ M	2020	2021	2022	2023	2024	2025Q3
Revenues	3,580	4,684	5,650	6,911	9,688	8,557
Gross Profit	1,456	1,667	2,084	2,201	2,906	2,768
Operating Expenses	991	1,112	1,374	1,483	1,790	1,619
Operating Income	465	555	710	718	1116	1,149
Income Before Tax	389	524	736	860	1277	1,073
Net Income	305	420	568	650	927	780
EPS	**3.80**	**5.23**	**7.08**	**8.10**	**11.54**	**9.71**
Gross Margin	41%	36%	37%	32%	30%	32%
Operating Margin	13%	12%	13%	10%	12%	13%
Income Before Tax Margin	11%	11%	13%	12%	13%	13%

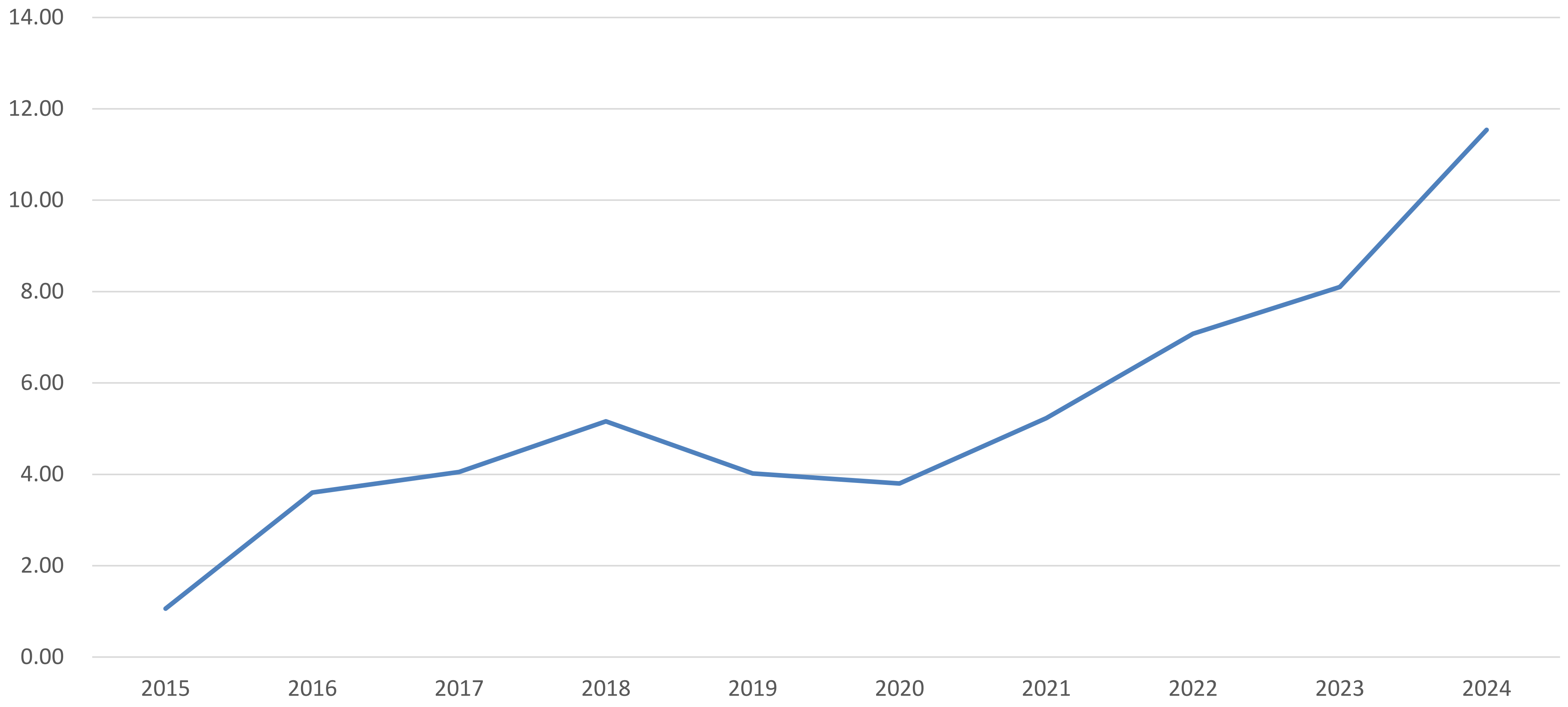
Revenue

Units NT $ M	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025Q3
Revenue	2,942	3,495	3,539	3,988	3,949	3,580	4,684	5,650	6,911	9,688	8,557



EPS

	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025Q3
EPS	1.06	3.6	4.05	5.16	4.02	3.8	5.23	7.08	8.1	**11.54**	**9.71**



Future Prospect

Industry Outlook

- The CAGR of the Semi. market size over the next 10 years is approximately 8%
- In 2025, the global Semi. market is expected to grow 11%
- Driven by demand in artificial intelligence (AI) and high-performance computing (HPC) applications, the semi. market in Taiwan:

Year	Market Size (Billion US$)	Groth Rate (%)
2025	181	15.4
2026	???	???

- 12-inch semi. advanced process continues to thrive
  - Front-End: 5nm、3nm、2nm、1nm
  - Advanced Package: Fan-Out、2.5D (CoWoS)、3D (SoIC)…etc

Industry Outlook – 2

- The CAGR of Advanced Packaging over the next 10 years is estimated at 11%.
- CoWoS production capacity is expanding substantially to meet the rising demand for AI chip applications
- AI applications are expanding from Data Centers to Edge Computing, Personal Devices
- China's semi. production capacity is expanding, intensifying price competition in mature process nodes.
- Compound Semi:
    - Investment in electric vehicles (EVs) and 5G is stagnant
    - Mobile phone demand is saturating, leading to reduced GaAs production
    - SiC demand gradually increases, with new capacities slowing down
    - Micro LED adoption is progressing slowly

Expansion Plan

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- 2023: New equipment production base in Hukou (off-site)
- 2024: Expansion of existing equipment production at Hukou Plant
- **2025 Q4: Wafer Reclaim Capacity 50K/Month at Hukou Plant**
- **2026 Q4: 9,000 M-Square new building (Plant II) for equipment manufacturing, and warehouse next to Hukou Plant (Plant I)**
- **2026 Q4: Wafer Reclaim Capacity 40K/Month at Hukou Plant**
- **2027 Q2: 22,000 M-Square new building for equipment manufacturing, and warehouse in Tainan (southern Taiwan)**
- 2027: Wafer Reclaim Capacity 50K/Month at Hukou Plant

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Thank You!

https://www.scientech.com.tw